SN74UVP1G37 Single Buffer/Driver With Schmitt-Trigger Input and Open-Drain Output

1 Features

- Extended low-voltage operation with 0.63V to 3.6V supply range
- Extended operating temperature range: –40°C to 125°C
- Low power consumption
  - Typical I_{CC} = 10nA
  - Typical input leakage I_I = 3nA
  - Typical output off-state leakage current I_{OZ} = 100nA
  - Typical partial-power-down I_{OFF} 0.2uA
- 3.6V tolerant input to support down translation
- Maximum t_{pd} of 9.5ns at 3.3V
- Drop-in compatible with AUP1G family and V_{CC} extended from 0.8V to 0.63V

2 Applications

- PC and notebooks
- Data center
- Building automation
- Mobile phones
- Wearables
- Wired networking

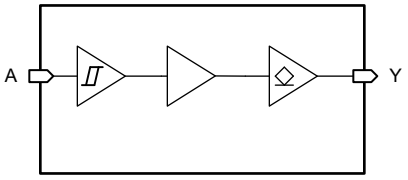
3 Description

The SN74UVP1G37 device is a buffer with a Schmitt-Trigger input and an Open-Drain output.

Package Information

PART NUMBER	PACKAGE(1)	PACKAGE SIZE(2)
SN74UVP1G37	DBV (SOT-23, 5)	2.90mm × 1.60mm
	DCK (SC-70, 5)	2.00mm × 1.25mm
	DRY (USON, 6)	1.45mm × 1.00mm
	DSF (X2SON, 6)	1.00mm × 1.00mm
	DPW (X2SON, 5)	0.80mm × 0.80mm

(1) For more information, see Section 11.
(2) The package size (length × width) is a nominal value and does not include pins.



Logic Diagram

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4 Pin Configuration and Functions

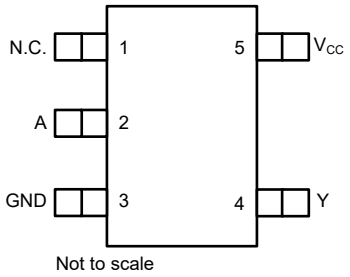


Figure 4-1. DBV or DCK Package, 5-Pin SOT-23 or SC-70 (Top View)

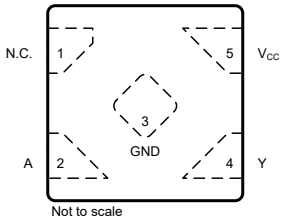


Figure 4-2. DPW Package, 5-Pin X2SON (Top View)

Table 4-1. Pin Functions

PIN		TYPE(1)	DESCRIPTION
NAME	DPW, DBV, DCK		
N.C.	1	—	Not internally connected
A	2	I	Input A
GND	3	G	Ground pin
Y	4	O	Output Y (push pull)
VCC	5	P	Power pin

(1) I = Input, O = Output, G = Ground, P = Power

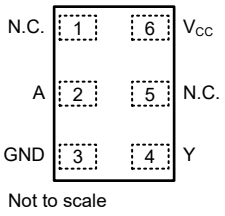


Figure 4-3. DRY or DSF Package, 5-Pin USON or X2SON (Top View)

Table 4-2. Pin Functions

PIN		TYPE(1)	DESCRIPTION
NAME	DSF, DRY		
N.C.	1, 5	—	Not internally connected
A	2	I	Input A
GND	3	G	Ground pin
Y	4	O	Output Y (push pull)
VCC	6	P	Power pin

(1) I = Input, O = Output, G = Ground, P = Power

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5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range		-0.5	6	V
V_I	Input voltage range(2)		-0.5	6	V
V_O	Output voltage range(2)		-0.5	V_{CC} + 0.5	V
V_O	Output voltage range (2)		-0.5	6	V
I_{IK}	Input clamp current	V_I < 0V		-50	mA
I_{OK}	Output clamp current	V_O < 0V		-50	mA
I_O	Continuous output current			±50	mA
I_O	Continuous output current through V_{CC} or GND			±100	mA
T_J	Junction temperature		-65	150	°C
T_{stg}	Storage temperature		-65	150	°C

(1) Operation outside the *Absolute Maximum Ratings* may cause permanent device damage. Absolute maximum ratings do not imply functional operation of the device at these or any other conditions beyond those listed under *Recommended Operating Conditions*. If briefly operating outside the *Recommended Operating Conditions* but within the *Absolute Maximum Ratings*, the device may not sustain damage, but it may not be fully functional. Operating the device in this manner may affect device reliability, functionality, performance, and shorten the device lifetime.
(2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

5.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001(1)	±2000	V
		Charged-device model (CDM), per ANSI/ESDA/JEDEC JS-002(2)	±1000	

(1) JEDEC document JEP155 states that 500V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250V CDM allows safe manufacturing with a standard ESD control process.

5.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

Specifications	Description	Condition	MIN	MAX	UNIT
V_{CC}	Supply voltage		0.63	3.6	V
V_I	Input voltage		0	5.5	V
V_O	Output voltage		0	5.5	V
I_{OL}	Low-level output current	V_{CC} = 0.63V		0.2	mA
		V_{CC} = 0.72V		0.5	
		V_{CC} = 0.9V		0.7	
		V_{CC} = 1.08V		1.1	
		V_{CC} = 1.35V		1.7	
		V_{CC} = 1.62V		1.9	
		V_{CC} = 2.3V		3.1	
		V_{CC} = 3.0V		4	
T_A	Operating free-air temperature		-40	125	°C

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5.4 Thermal Information

PACKAGE	PINS	THERMAL METRIC(1)						UNIT
		$R_{\theta JA}$	$R_{\theta JC(top)}$	$R_{\theta JB}$	Ψ_{JT}	Ψ_{JB}	$R_{\theta JC(bot)}$	
DBV (SOT-23, 5)	5	298.6	240.2	134.6	114.5	133.9	n/a	°C/W
DCK (SC-70, 5)	5	314.4	128.7	100.6	7.1	99.8	n/a	°C/W
DRY (USON, 6)	6	554.9	385.4	388.2	159.0	384.1	n/a	°C/W
DSF (X2SON, 6)	6	407.1	232.0	306.9	40.3	306.0	n/a	°C/W
DPW (X2SON, 5)	5	291.8	224.2	245.8	31.4	245.6	195.4	°C/W

(1) For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application note.

5.5 Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
V_{T+}	Positive-going input threshold voltage	0.63V	0.3		0.42	V
		0.65V	0.31		0.43	
		0.72V	0.35		0.47	
		0.9V	0.45		0.57	
		1.08V	0.56		0.68	
		1.35V	0.71		0.87	
		1.5V	0.79		0.98	
		1.62V	0.86		1.07	
		1.95V	1.07		1.33	
		2.3V	1.33		1.62	
		2.5V	1.47		1.78	
		2.7V	1.63		1.94	
		3V	1.86		2.18	
		3.6V	2.33		2.67	
V_{T-}	Negative-going input threshold voltage	0.63V	0.15		0.31	V
		0.65V	0.16		0.32	
		0.72V	0.19		0.34	
		0.9V	0.25		0.42	
		1.08V	0.32		0.49	
		1.35V	0.42		0.59	
		1.5V	0.48		0.64	
		1.62V	0.52		0.68	
		1.95V	0.6		0.78	
		2.3V	0.69		0.88	
		2.5V	0.73		0.92	
		2.7V	0.78		0.97	
		3V	0.85		1.03	
		3.6V	1.01		1.21	

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5.5 Electrical Characteristics (continued)

over operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
ΔV_T	Hysteresis ($V_{T+} - V_{T-}$)	0.63V	0.08		0.18	V
		0.65V	0.08		0.18	
		0.72V	0.09		0.2	
		0.9V	0.13		0.24	
		1.08V	0.17		0.27	
		1.35V	0.23		0.33	
		1.5V	0.27		0.41	
		1.62V	0.3		0.47	
		1.95V	0.38		0.65	
		2.3V	0.53		0.84	
		2.5V	0.63		0.94	
		2.7V	0.74		1.04	
		3V	0.92		1.19	
		3.6V	1.26		1.49	
V_{OL}	I_{OL}= 20µA	0.63V to 3.6V			0.15	V
	I_{OL}= 0.7mA	1.0V			0.35	
	I_{OL}= 1.1mA	1.2V			0.25	
	I_{OL}= 1.7mA	1.5V			0.23	
	I_{OL}= 1.9mA	1.65V			0.23	
	I_{OL}= 3.1mA	2.3V			0.26	
	I_{OL}= 3.5mA	2.7V			0.27	
	I_{OL}= 4mA	3V			0.29	
I_I	V_I = V_{CC} or GND	V_{CC} = 0V to 3.6V		±0.003	±0.5	µA
I_{OFF}	V_I or V_O = V_{CC}	V_{CC} = 0V		±0.2	±1	µA
I_{OZ}	V_O = V_{CC} or GND	3.6V		±0.1	±1.5	µA
I_{CC}	V_I = V_{CC} or GND, I_O = 0	V_{CC} = 0.63V to 3.6V		0.01	1.4	µA
ΔI_{CC}	One input at V_{CC} - 0.6V, other inputs at V_{CC} or GND	3.3V			60	µA
C_I	V_I = V_{CC} or GND	3.3V		4.4		pF
C_O	V_O = V_{CC} or GND	3.3V		2.59		pF

5.6 Switching Characteristics

over operating free-air temperature range; typical values measured at T_A = 25°C (unless otherwise noted). See *Parameter Measurement Information*

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CONDITION	V_{CC}	MIN	TYP	MAX	UNIT
t_{pd}	A	Y	C_L = 5pF	0.7V ± 0.07V			336.3	ns
				0.8V ± 0.08V			135.7	ns
			C_L = 10pF	1.0V ± 0.1V			36.5	ns
				1.2V ± 0.12V			20.2	ns
			C_L = 15pF	1.5V ± 0.15V			8.4	ns
				1.8V ± 0.18V			8	ns
			C_L = 30pF	2.5V ± 0.2V			8.4	ns
				3.3V ± 0.3V			11.2	ns

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over operating free-air temperature range; typical values measured at T_A = 25°C (unless otherwise noted). See *Parameter Measurement Information*

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CONDITION	V_{CC}	MIN	TYP	MAX	UNIT
C_{pd}			f = 10MHz	0.7V		0.9		pF
				0.8V		1		pF
				1.0V		1.1		pF
				1.2V		1.1		pF
				1.5V		1.2		pF
				1.8V		1.4		pF
				2.5V		1.7		pF
				3.3V		2		pF

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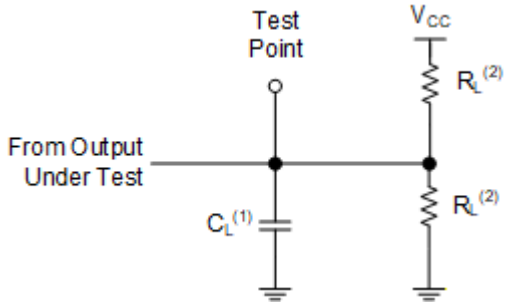
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6 Parameter Measurement Information

Phase relationships between waveforms were chosen arbitrarily for the examples listed in the following table. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1MHz, Z_O = 50Ω, t_t < 3ns.

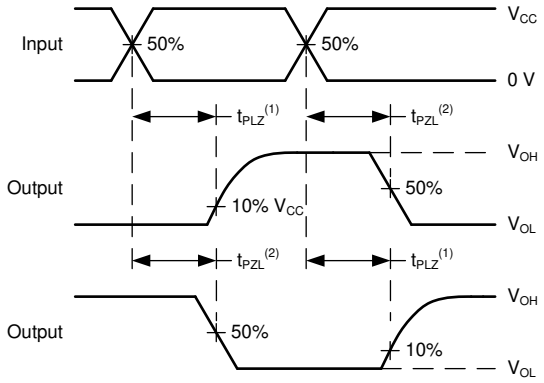
The outputs are measured individually with one input transition per measurement.

TEST	R_L	C_L	ΔV	V_{CC}
t_{pd}	20KΩ	5pF	0.07V	0.7V
			0.08V	0.8V
		10pF	0.1V	1.0V
	5KΩ	10pF	0.12V	1.2V
		15pF	0.15V	1.5V
			0.18V	1.8V
		30pF	0.2V	2.5V
			0.3V	3.3V



(1) C_L includes probe and test-fixture capacitance.
(2) R_L = 5kΩ or 20kΩ for enable and disable time measurement. R_L = 1MΩ for measuring propagation delays, setup and hold times, and pulse width.

Figure 6-1. Load Circuit for Open-Drain Outputs



(1) If R_L = 5kΩ, the time between t_{PLZ} and t_{PZL} is the same as disable and enable time.
(2) If R_L = 1MΩ, t_{PLZ} and t_{PZL} are the same as t_{pd}.

Figure 6-2. Voltage Waveforms Propagation Delays

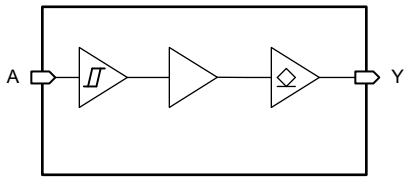
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7 Detailed Description

7.1 Overview

The SN74UVP1G37 device contains one open-drain buffer/driver with a maximum sink current of 32mA. This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs when the device is powered down. This inhibits current backflow into the device which prevents damage to the device.

7.2 Functional Block Diagram



7.3 Feature Description

7.3.1 Open-Drain CMOS Outputs

Open-drain outputs are included in SN74UVP1G37. Open-drain outputs can only drive the output low. When in the high logical state, outputs are in a high-impedance state, meaning outputs neither source nor sink current (with the exception of minor leakage current as defined in the *Electrical Characteristics* table). In the high-impedance state, the output voltage is not controlled by SN74UVP1G37 and is dependent on external factors.

Because of the high-impedance state, an external pull-up resistor is required to define a logic high. Without a pull-up resistor, the output will float and have an undefined logic level. The resistor value depends on factors like parasitic capacitance and power consumption; typically, a 10kΩ resistor is suitable.

The drive capability of SN74UVP1G37 can create fast edges into light loads, so consider routing and load conditions to prevent ringing. Additionally, outputs can drive higher currents than SN74UVP1G37 is designed to handle continuously. Limit the device output power to avoid damage due to overcurrent. Follow the electrical and thermal limits defined in the *Absolute Maximum Ratings* at all times. See the *Recommended Operating Conditions* table for the maximum output voltage that can be externally connected to SN74UVP1G37.

Leave unused open-drain CMOS outputs disconnected.

7.3.2 CMOS Schmitt-Trigger Inputs

This device includes inputs with the Schmitt-trigger architecture. These inputs are high impedance and are typically modeled as a resistor in parallel with the input capacitance given in the *Electrical Characteristics* table from the input to ground. The worst case resistance is calculated with the maximum input voltage, given in the *Absolute Maximum Ratings* table, and the maximum input leakage current, given in the *Electrical Characteristics* table, using Ohm's law (R = V ÷ I).

The Schmitt-trigger input architecture provides hysteresis as defined by ΔV_T in the *Electrical Characteristics* table, which makes this device extremely tolerant to slow or noisy inputs. While the inputs can be driven much slower than standard CMOS inputs, properly terminating unused inputs is still recommended. Driving the inputs with slow transitioning signals increases dynamic current consumption of the device. For additional information regarding Schmitt-trigger inputs, please see *Understanding Schmitt Triggers*.

7.4 Device Functional Modes

Function Table

INPUT(1) A	OUTPUT(2) Y
H	Z
L	L

(1) H = High voltage level, L = Low voltage level

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(2) H = Driving high, Z = High-impedance state

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8 Application and Implementation

Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

8.1 Application Information

In this application, an open-drain buffer is used to drive an LED as shown in Figure 8-1.

8.2 Typical Application

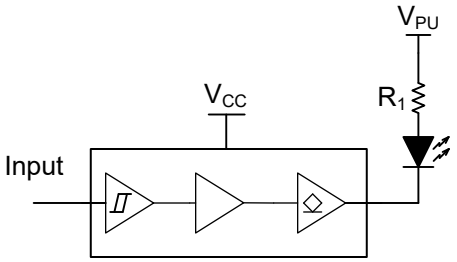


Figure 8-1. Typical Application Block Diagram

8.2.1 Design Requirements

8.2.1.1 Power Considerations

Verify that the desired supply voltage is within the range specified in the *Electrical Characteristics*. The supply voltage sets the device electrical characteristics, as described in the *Electrical Characteristics* section.

The positive voltage supply must be capable of sourcing current equal to the maximum static supply current, I_{CC}, listed in the *Electrical Characteristics*, and any transient current required for switching.

The ground must be capable of sinking current equal to the total current to be sunk by all outputs of the SN74UVP1G37 plus the maximum supply current, I_{CC}, listed in the *Electrical Characteristics*, and any transient current required for switching. The logic device can only sink as much current that can be sunk into the ground connection. Verify that the maximum total current through GND listed in the *Absolute Maximum Ratings* is not exceeded.

The SN74UVP1G37 can drive a load with a total capacitance less than or equal to 30nF while still meeting all of the data sheet specifications. Larger capacitive loads can be applied; however, TI recommends adding a series resistor between the output and capacitor to prevent excessive current.

The SN74UVP1G37 can drive a load with total resistance described by $R_L \geq V_O / I_O$, with the output voltage and current defined in the *Electrical Characteristics* table with V_{OL}. When outputting in the HIGH state, the output voltage in the equation is defined as the difference between the measured output voltage and the supply voltage at the V_{CC} pin.

Total power consumption can be calculated using the information provided in the *CMOS Power Consumption and Cpd Calculation* application note.

Thermal increase can be calculated using the information provided in the *Thermal Characteristics of Standard Linear and Logic (SLL) Packages and Devices* application note.

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CAUTION

The maximum junction temperature, $T_{J(max)}$ listed in the *Absolute Maximum Ratings*, is an additional limitation to prevent damage to the device. Do not violate any values listed in the *Absolute Maximum Ratings*. These limits are provided to prevent damage to the device.

8.2.1.2 Input Considerations

Input signals must cross $V_{t-(min)}$ to be considered a logic LOW, and $V_{t+(max)}$ to be considered a logic HIGH. Do not exceed the maximum input voltage range found in the *Absolute Maximum Ratings*.

Unused inputs must be terminated to either V_{CC} or ground. The unused inputs can be directly terminated if the input is completely unused, or the inputs can be connected with a pullup or pulldown resistor if the input is used sometimes, but not always. A pullup resistor is used for a default state of HIGH, and a pulldown resistor is used for a default state of LOW. The drive current of the controller, leakage current into the SN74UVP1G37 (as specified in the *Electrical Characteristics*), and the desired input transition rate limits the resistor size. A 10kΩ resistor value is often used due to these factors.

The SN74UVP1G37 has no input signal transition rate requirements because the device has Schmitt-Trigger inputs.

Another benefit to having Schmitt-Trigger inputs is the ability to reject noise. Noise with a large enough amplitude can still cause issues. To know how much noise is too much, please refer to the $\Delta V_{T(min)}$ in the Electrical Characteristics . This hysteresis value provides the peak-to-peak limit.

Unlike what happens with standard CMOS inputs, Schmitt-Trigger inputs can be held at any valid value without causing huge increases in power consumption. The typical additional current caused by holding an input at a value other than V_{CC} or ground is plotted in the Typical Characteristics .

Refer to the *Feature Description* for additional information regarding the inputs for this device.

8.2.1.3 Output Considerations

The ground voltage is used to produce the output LOW voltage. Sinking current into the output increases the output voltage as specified by the V_{OL} specification in the *Electrical Characteristics*.

Open-drain outputs can be connected together directly to produce a wired-AND configuration or for additional output drive strength.

Unused outputs can be left floating. Do not connect outputs directly to V_{CC} or ground.

Refer to the *Feature Description* section for additional information regarding the outputs for this device.

8.2.2 Detailed Design Procedure

1. Add a decoupling capacitor from V_{CC} to GND. The capacitor needs to be placed physically close to the device and electrically close to both the V_{CC} and GND pins. An example layout is shown in the *Layout* section.
2. Verify that the capacitive load at the output is ≤ 50pF. Low load capacitance can be accomplished by providing short, appropriately sized traces from the SN74UVP1G37 to the receiving device.
3. Verify that the resistive load at the output is larger than (V_{CC} / $I_{O(max)}$)Ω. Never violate the maximum output current from the *Absolute Maximum Ratings*. Most CMOS inputs have a resistive load measured in MΩ; much larger than the minimum calculated previously.
4. Thermal issues are rarely a concern for logic gates; however, the power consumption and thermal increase can be calculated using the steps provided in the *CMOS Power Consumption and Cpd Calculation* application note.

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8.2.3 Application Curves

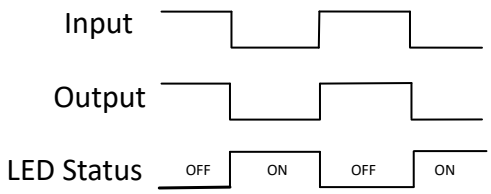


Figure 8-2. Application Curve

8.3 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the *Recommended Operating Conditions*. Each V_{CC} terminal must have a good bypass capacitor to prevent power disturbance.

A 0.1µF capacitor is recommended for this device. It is acceptable to parallel multiple bypass capacitors to reject different frequencies of noise. The 0.1µF and 1µF capacitors are commonly used in parallel. The bypass capacitor must be installed as close to the power terminal as possible for best results.

8.4 Layout

8.4.1 Layout Guidelines

- Bypass capacitor placement
  - Place near the positive supply terminal of the device
  - Provide an electrically short ground return path
  - Use wide traces to minimize impedance
  - Keep the device, capacitors, and traces on the same side of the board whenever possible
- Signal trace geometry
  - 8mil to 12mil trace width
  - Lengths less than 12cm to minimize transmission line effects
  - Avoid 90° corners for signal traces
  - Use an unbroken ground plane below signal traces
  - Flood fill areas around signal traces with ground
  - Parallel traces must be separated by at least 3x dielectric thickness
  - For traces longer than 12cm
    - Use impedance controlled traces
    - Source-terminate using a series damping resistor near the output
    - Avoid branches; buffer each signal that must branch separately

8.4.2 Layout Example

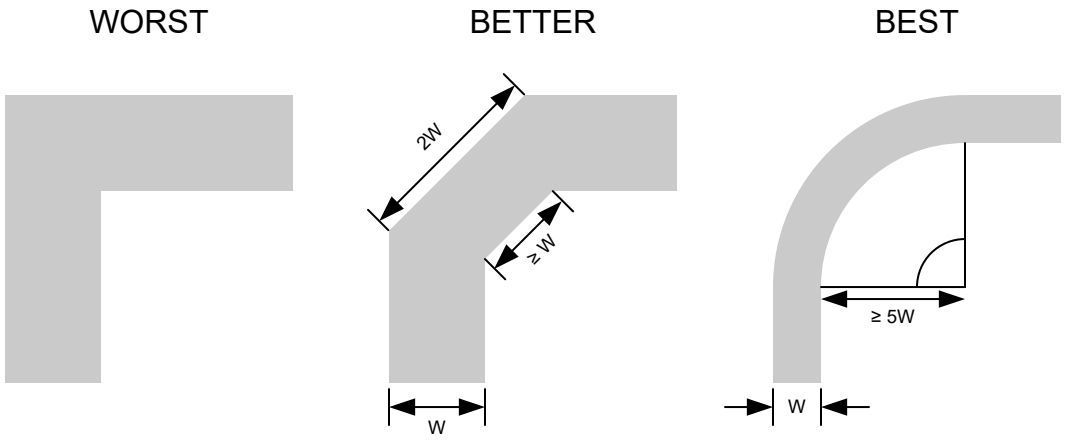


Figure 8-3. Example Trace Corners for Improved Signal Integrity

ADVANCE INFORMATION

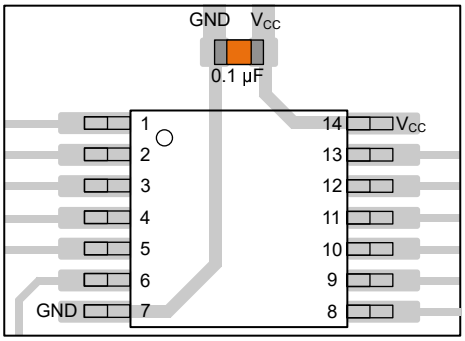


Figure 8-4. Example Bypass Capacitor Placement for TSSOP and Similar Packages

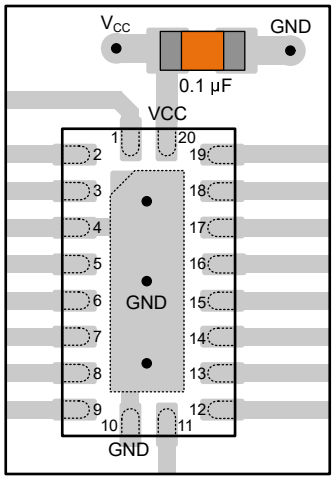


Figure 8-5. Example Bypass Capacitor Placement for WQFN and Similar Packages

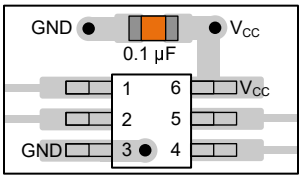


Figure 8-6. Example Bypass Capacitor Placement for SOT, SC70 and Similar Packages

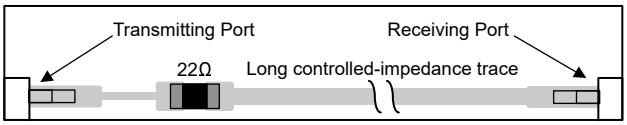


Figure 8-7. Example Damping Resistor Placement for Improved Signal Integrity

ADVANCE INFORMATION

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9 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

9.1 Documentation Support

9.1.1 Related Documentation

For related documentation, see the following:

- Texas Instruments, *CMOS Power Consumption and C_{pd} Calculation* application note
- Texas Instruments, *Designing With Logic* application note
- Texas Instruments, *Thermal Characteristics of Standard Linear and Logic (SLL) Packages and Devices* application note

9.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

9.3 Support Resources

TI E2E™ support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

9.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.
All trademarks are the property of their respective owners.

9.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

9.6 Glossary

TI Glossary	This glossary lists and explains terms, acronyms, and definitions.

10 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

DATE	REVISION	NOTES
August 2026	*	Initial Release

ADVANCE INFORMATION

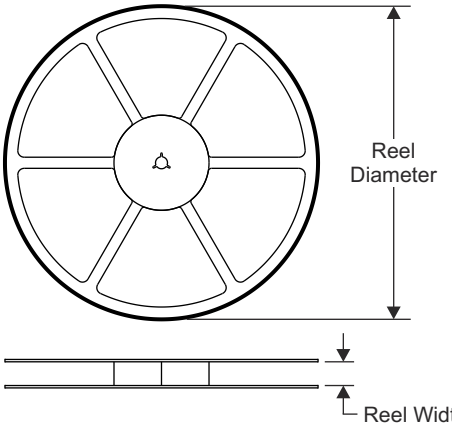
ADVANCE INFORMATION

11 Mechanical, Packaging, and Orderable Information

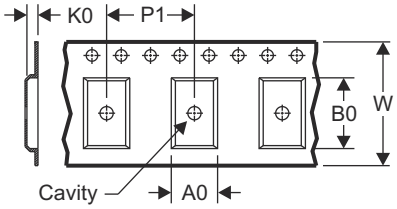
The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

11.1 Tape and Reel Information

REEL DIMENSIONS

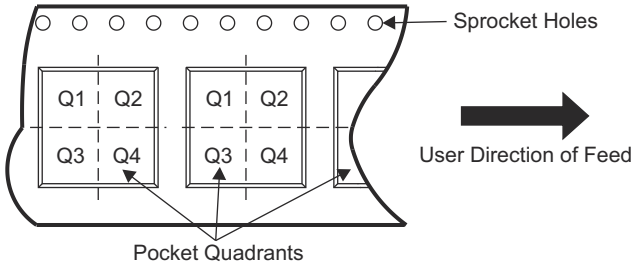


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

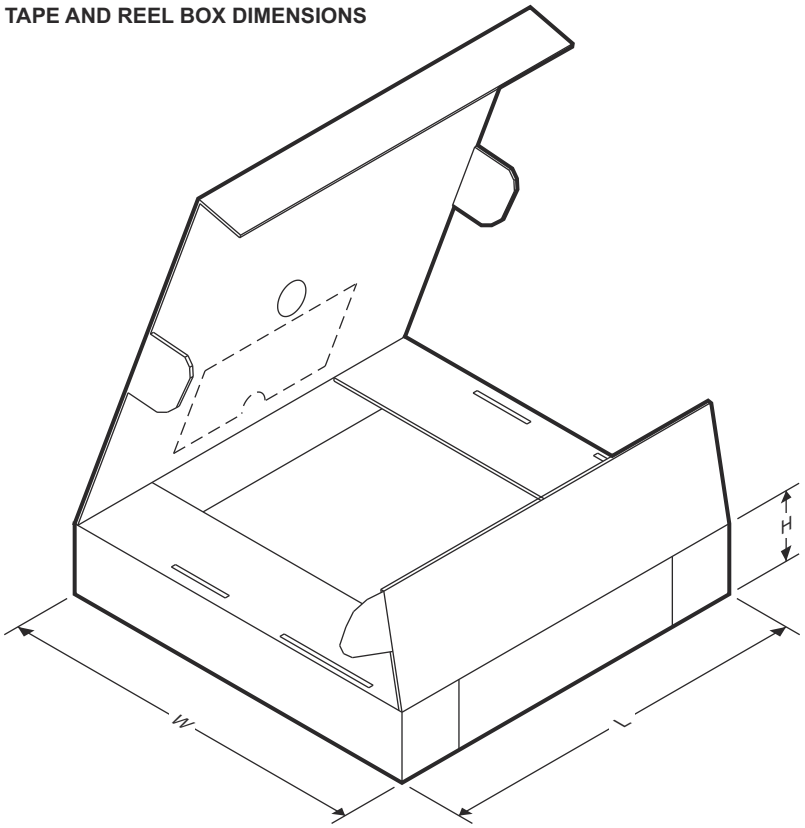
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
PSN74UVP1G37DBVR	SOT-23	DBV	5	3000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
PSN74UVP1G37DCKR	SC70	DCK	5	3000	178.0	8.4	2.25	2.45	1.2	4.0	8.0	Q3
PSN74UVP1G37DPWR	X2SON	DPW	5	3000	178.0	8.4	0.91	0.91	0.5	2.0	8.0	Q3
PSN74UVP1G37DRYR	USON	DRY	5	5000	180.0	9.5	1.15	1.6	0.75	4.0	8.0	Q1
PSN74UVP1G37DSFR	USON	DSF	5	5000	180.0	8.4	1.16	1.16	0.5	4.0	8.0	Q2

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TAPE AND REEL BOX DIMENSIONS



Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
PSN74UVP1G37DBVR	SOT-23	DBV	5	3000	208.0	191.0	35.0
PSN74UVP1G37DCKR	SC70	DCK	5	3000	208.0	191.0	35.0
PSN74UVP1G37DPWR	X2SON	DPW	5	3000	205.0	200.0	33.0
PSN74UVP1G37DRYR	USON	DRY	5	5000	184.0	184.0	19.0
PSN74UVP1G37DSFR	USON	DSF	5	5000	210.0	185.0	35.0

ADVANCE INFORMATION

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ADVANCE INFORMATION

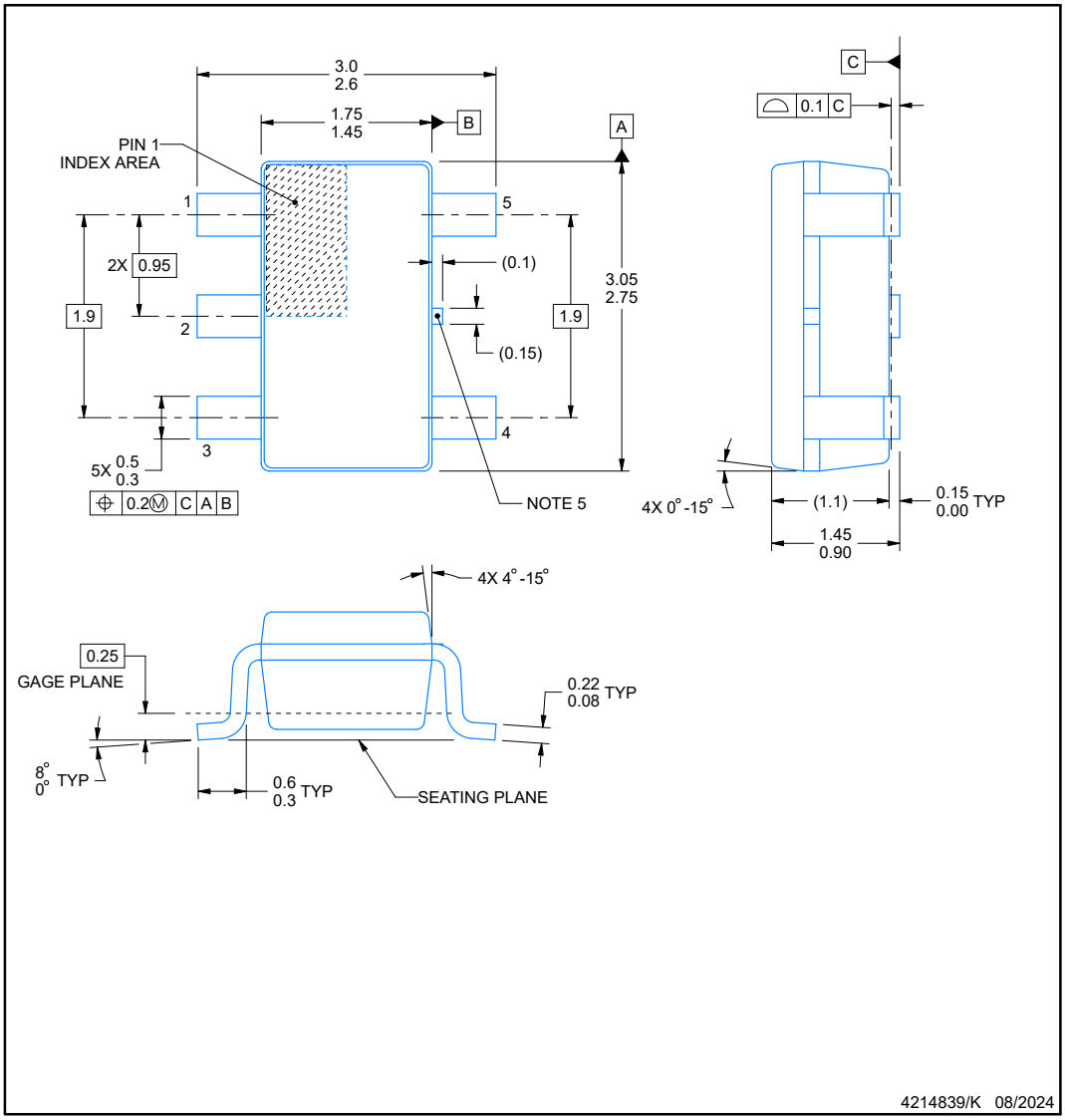
11.2 Mechanical Data



PACKAGE OUTLINE

DBV0005A — **SOT-23 - 1.45 mm max height**

SMALL OUTLINE TRANSISTOR



NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Refernce JEDEC MO-178.
4. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25 mm per side.
5. Support pin may differ or may not be present.

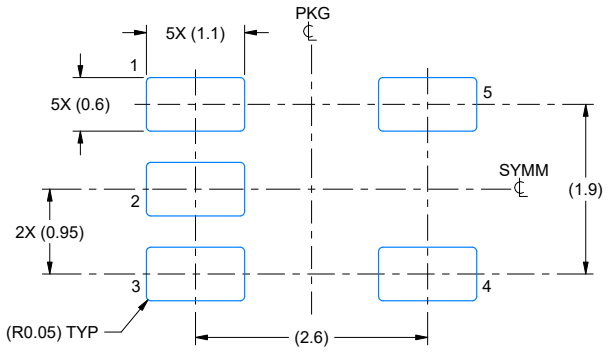
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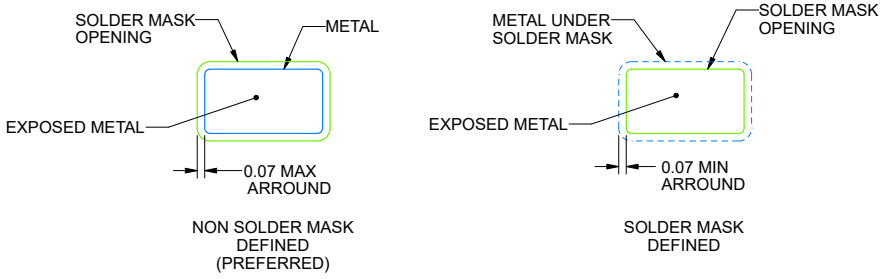
EXAMPLE BOARD LAYOUT

DBV0005A — **SOT-23 - 1.45 mm max height**

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:15X



SOLDER MASK DETAILS

4214839/K 08/2024

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

ADVANCE INFORMATION

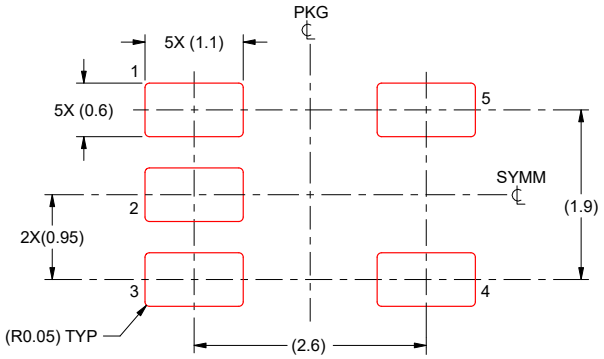
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ADVANCE INFORMATION

EXAMPLE STENCIL DESIGN

DBV0005A — **SOT-23 - 1.45 mm max height**

SMALL OUTLINE TRANSISTOR



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:15X

4214839/K 08/2024

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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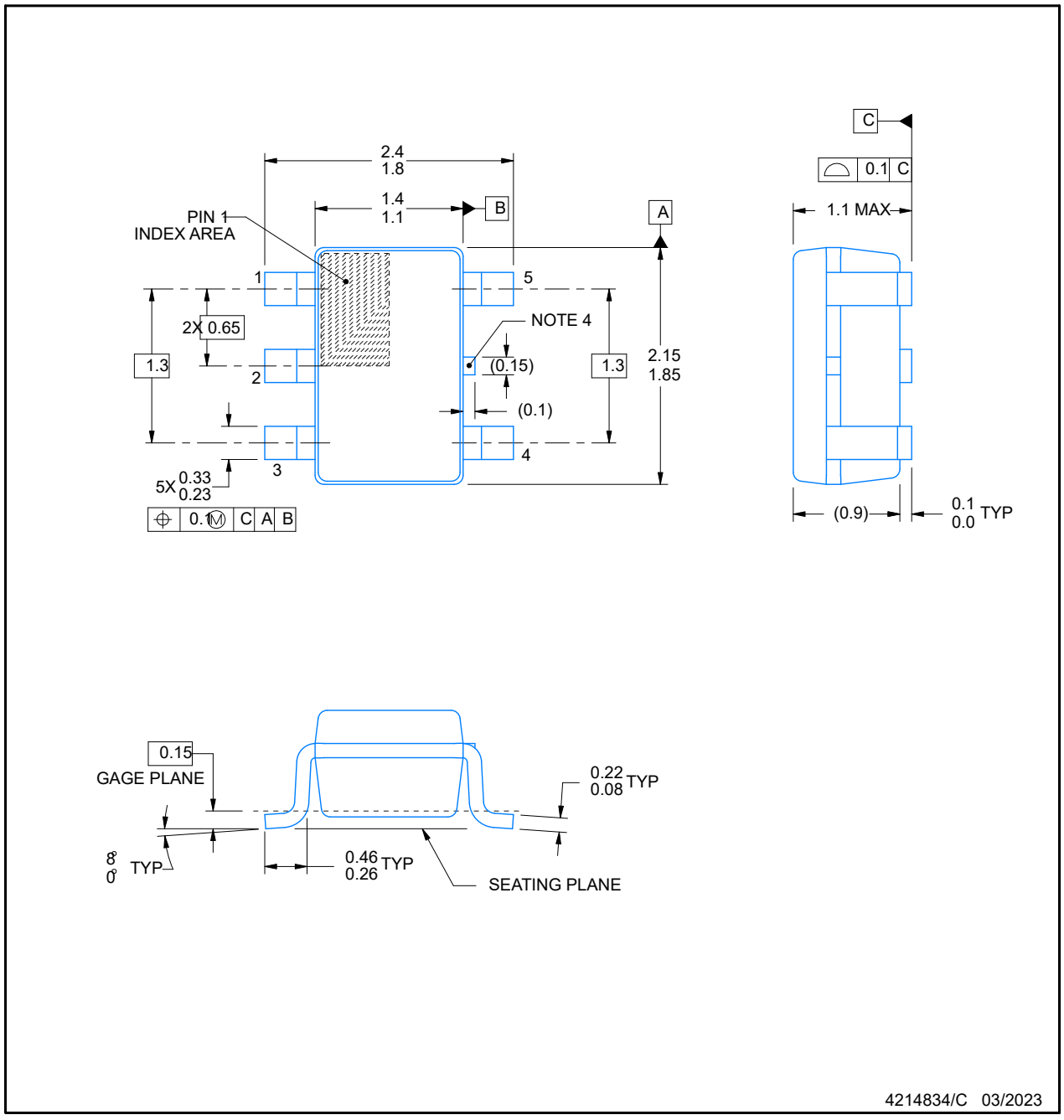


PACKAGE OUTLINE

DCK0005A

SOT - 1.1 max height

SMALL OUTLINE TRANSISTOR



4214834/C 03/2023

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dim ensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Refernce JEDEC MO-203.
4. Support pin may differ or may not be present.

ADVANCE INFORMATION

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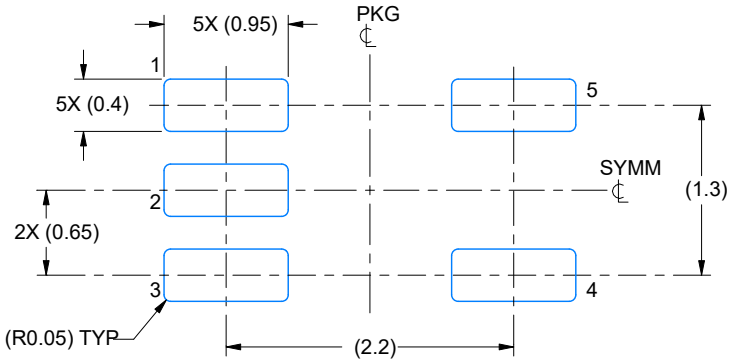
EXAMPLE BOARD LAYOUT

DCK0005A

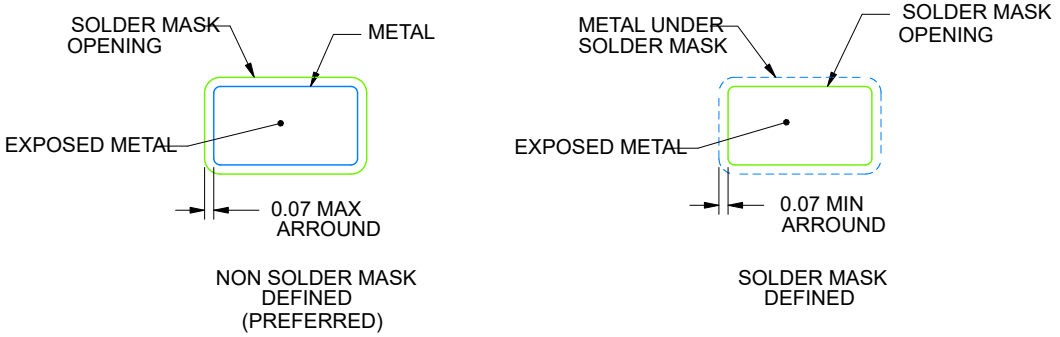
SOT - 1.1 max height

SMALL OUTLINE TRANSISTOR

ADVANCE INFORMATION



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:18X



SOLDER MASK DETAILS

4214834/C 03/2023

NOTES: (continued)

4. Publication IPC-7351 may have alternate designs.
5. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

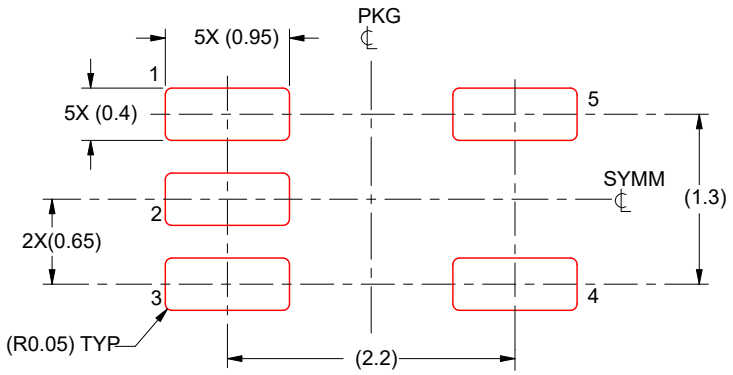
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EXAMPLE STENCIL DESIGN

DCK0005A

SOT - 1.1 max height

SMALL OUTLINE TRANSISTOR



SOLDER PASTE EXAMPLE
BASED ON 0.125 THICK STENCIL
SCALE:18X

4214834/C 03/2023

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
7. Board assembly site may have different recommendations for stencil design.

ADVANCE INFORMATION

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ADVANCE INFORMATION

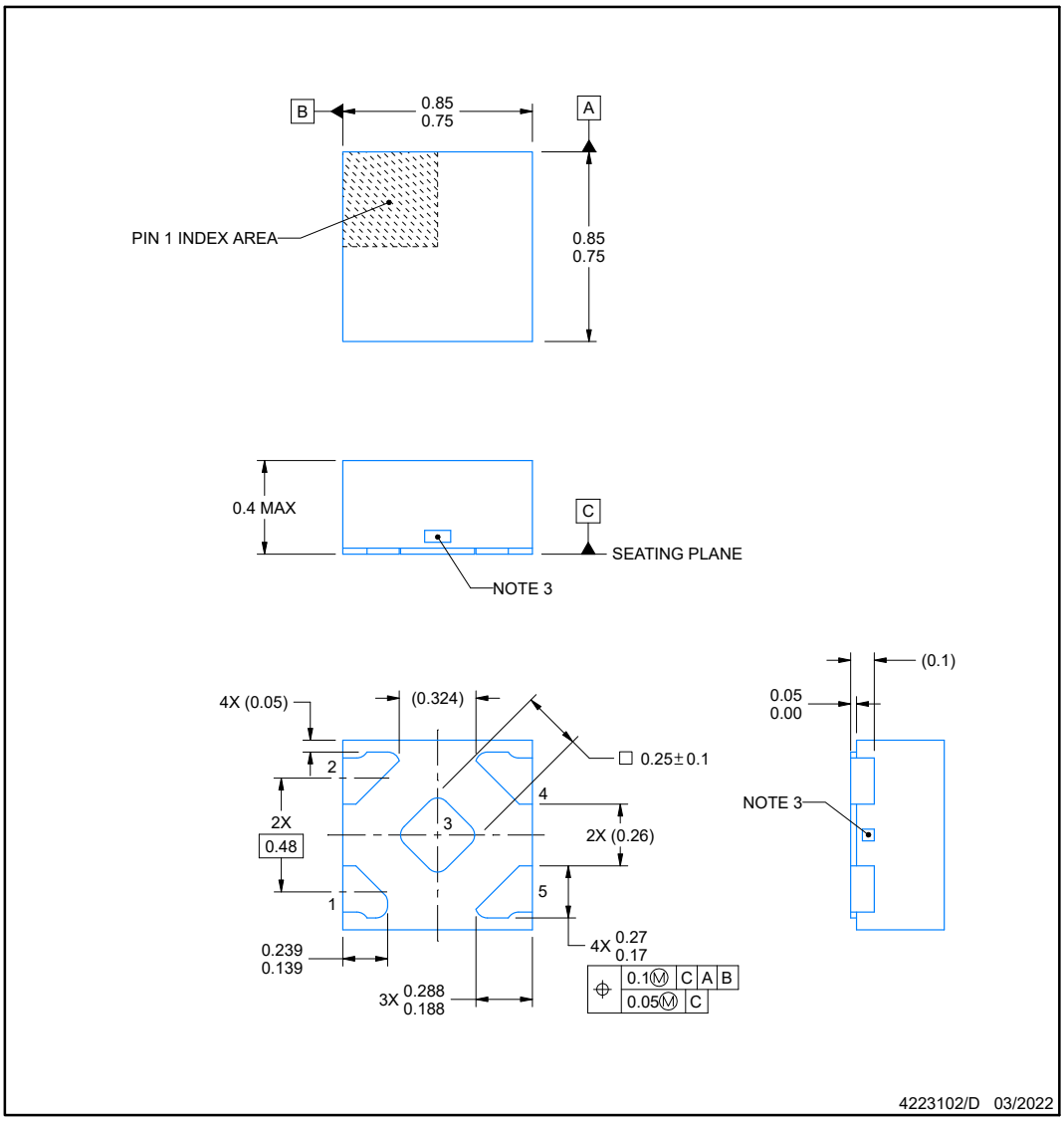
PACKAGE OUTLINE

DPW0005A



X2SON - 0.4 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The size and shape of this feature may vary.

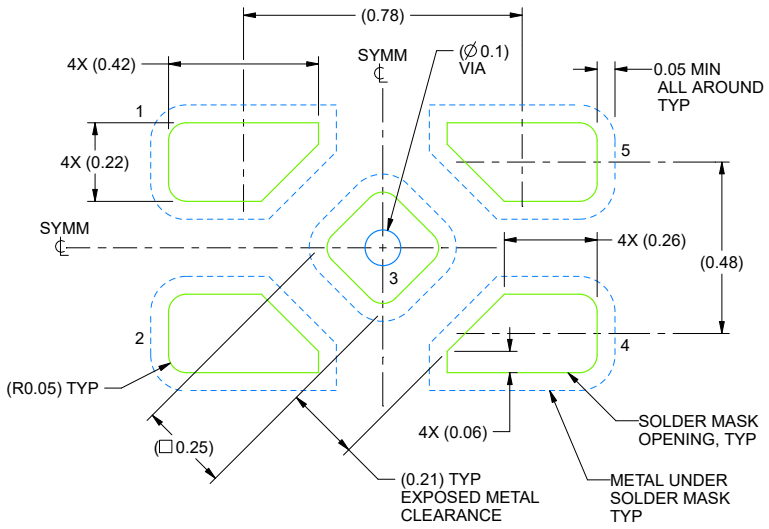
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EXAMPLE BOARD LAYOUT

DPW0005A — **X2SON - 0.4 mm max height**

PLASTIC SMALL OUTLINE - NO LEAD



LAND PATTERN EXAMPLE
SOLDER MASK DEFINED
SCALE:60X

4223102/D 03/2022

NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, refer to QFN/SON PCB application note in literature No. SLUA271 (www.ti.com/lit/slua271).

ADVANCE INFORMATION

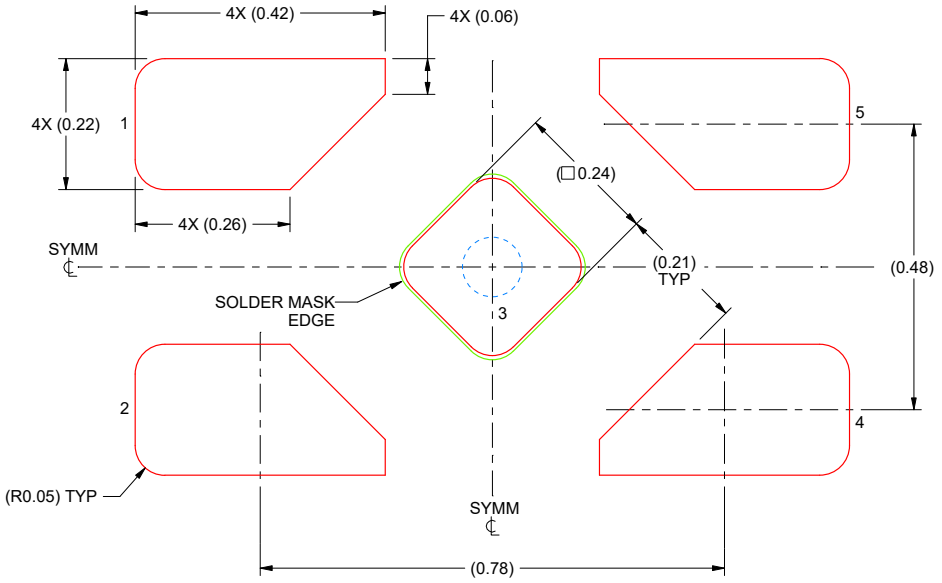
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ADVANCE INFORMATION

EXAMPLE STENCIL DESIGN

DPW0005A — **X2SON - 0.4 mm max height**

PLASTIC SMALL OUTLINE - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL

EXPOSED PAD 3
92% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
SCALE:100X

4223102/D 03/2022

NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

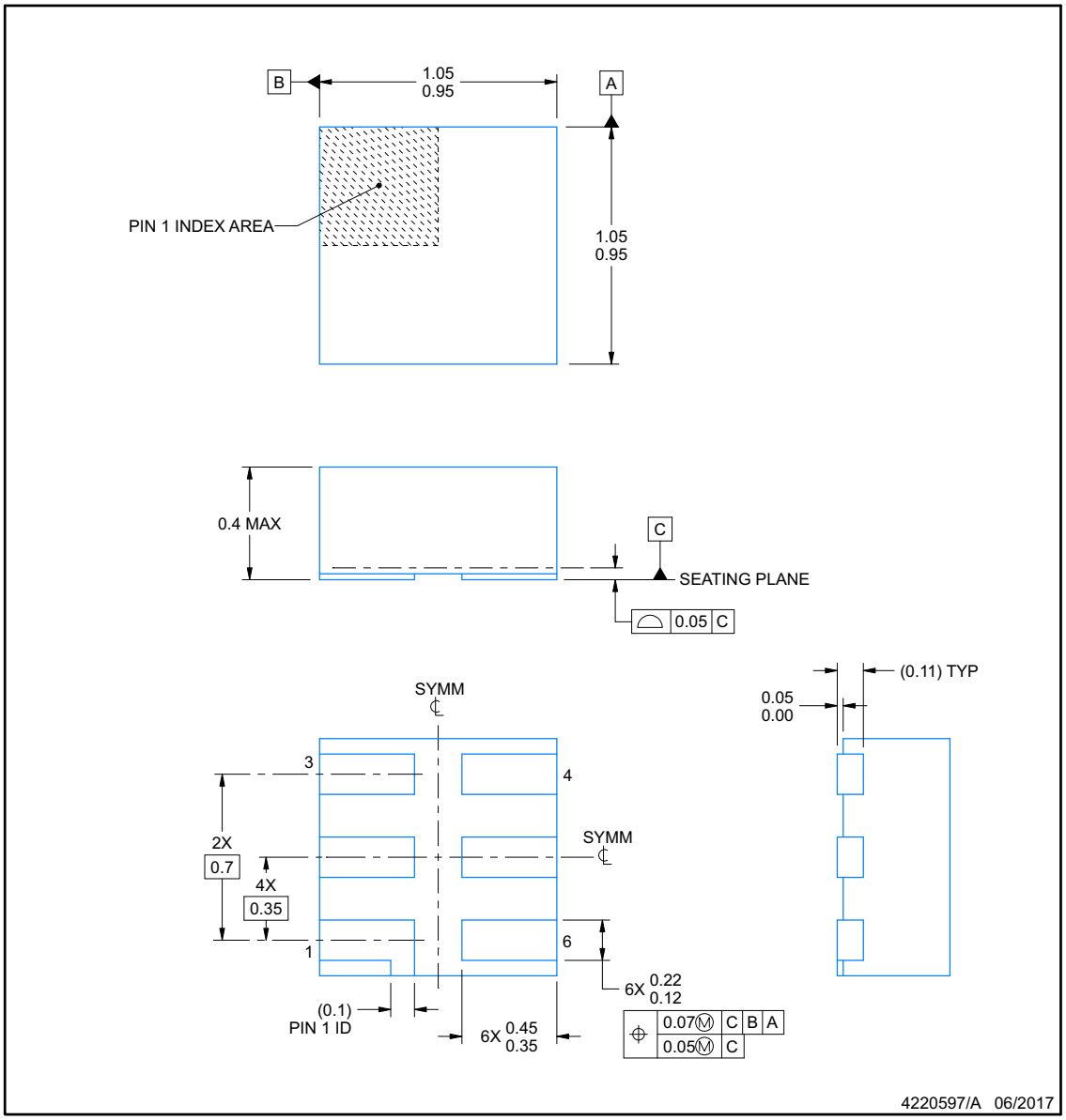
Copyright © 2026 Texas Instruments Incorporated

PACKAGE OUTLINE

DSF0006A

X2SON - 0.4 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC registration MO-287, variation X2AAF.

ADVANCE INFORMATION

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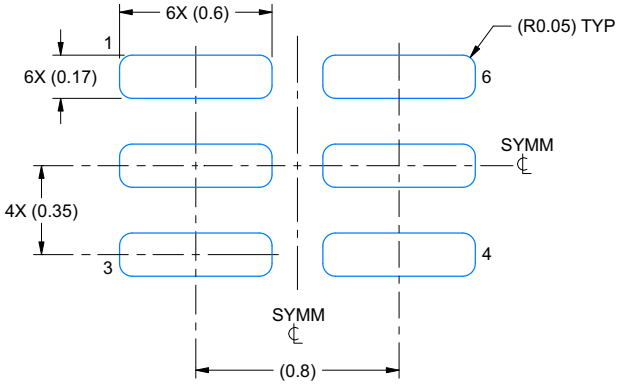
ADVANCE INFORMATION

EXAMPLE BOARD LAYOUT

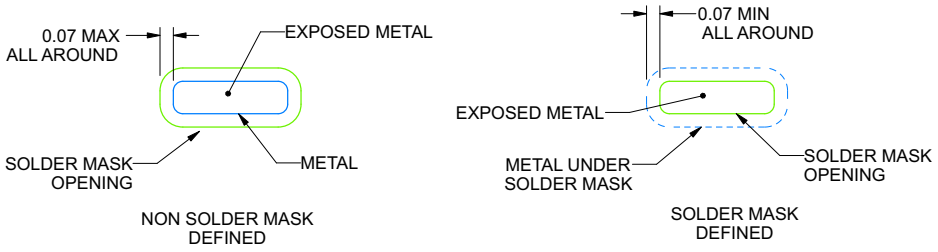
DSF0006A

X2SON - 0.4 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:40X



SOLDER MASK DETAILS

4220597/A 06/2017

NOTES: (continued)

4. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).

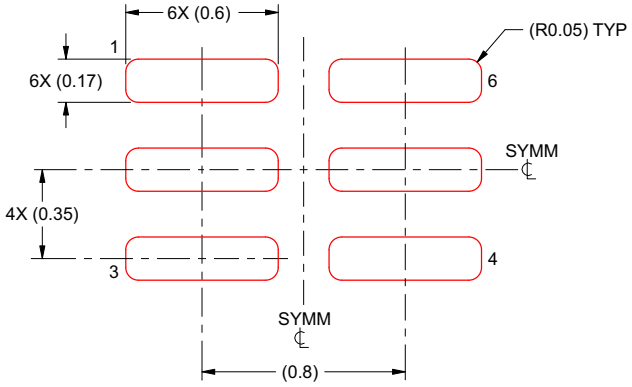
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EXAMPLE STENCIL DESIGN

DSF0006A

X2SON - 0.4 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
SCALE:40X

4220597/A 06/2017

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

ADVANCE INFORMATION

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ADVANCE INFORMATION

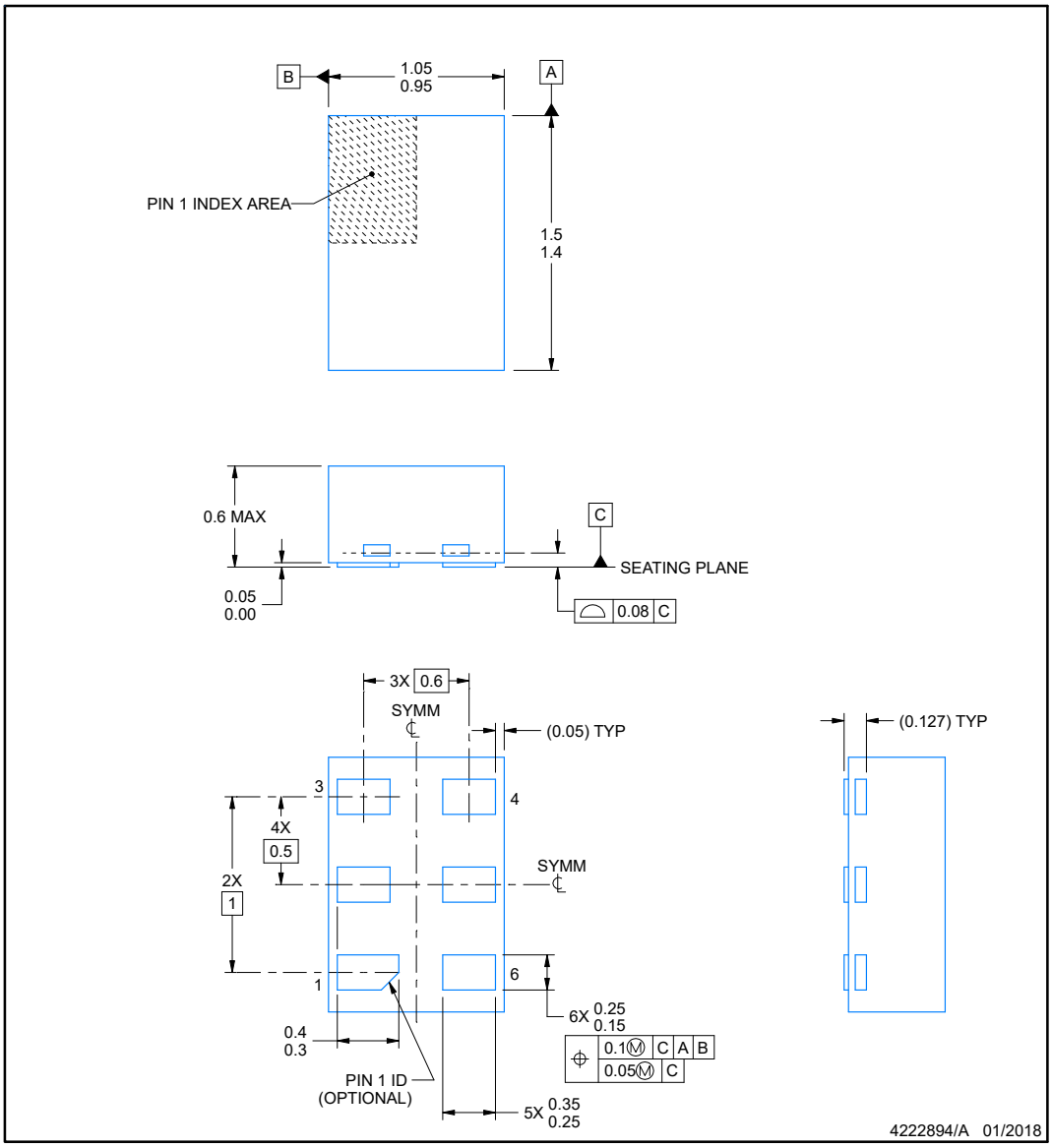
PACKAGE OUTLINE

DRY0006A



USON - 0.6 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



NOTES:

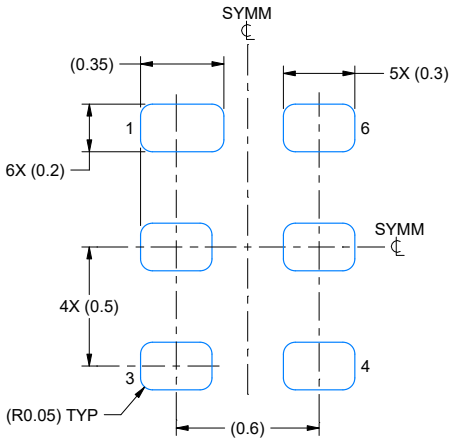
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

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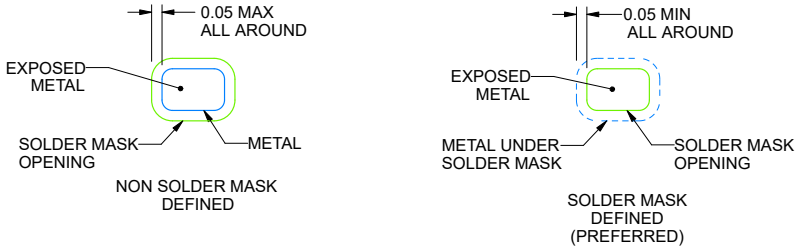
EXAMPLE BOARD LAYOUT

DRY0006A — **USON - 0.6 mm max height**

PLASTIC SMALL OUTLINE - NO LEAD



LAND PATTERN EXAMPLE
1:1 RATIO WITH PKG SOLDER PADS
EXPOSED METAL SHOWN
SCALE:40X



SOLDER MASK DETAILS

4222894/A 01/2018

NOTES: (continued)

3. For more information, see QFN/SON PCB application report in literature No. SLUA271 (www.ti.com/lit/slua271).

ADVANCE INFORMATION

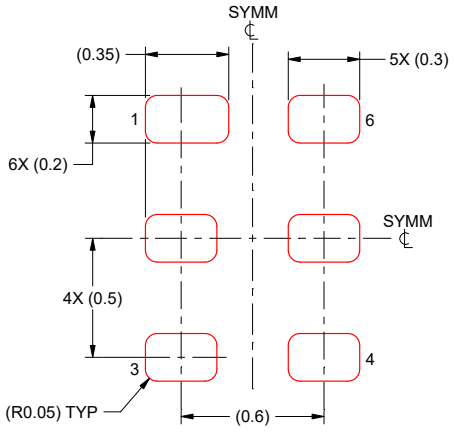
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ADVANCE INFORMATION

EXAMPLE STENCIL DESIGN

DRY0006A — **USON - 0.6 mm max height**

PLASTIC SMALL OUTLINE - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.075 - 0.1 mm THICK STENCIL
SCALE:40X

4222894/A 01/2018

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
PSN74UVP1G37DBVR	Active	Preproduction	SOT-23 (DBV) | 5	3000 | LARGE T&R	-	Call TI	Call TI	-	
PSN74UVP1G37DCKR	Active	Preproduction	SC70 (DCK) | 5	3000 | LARGE T&R	-	Call TI	Call TI	-	
PSN74UVP1G37DPWR	Active	Preproduction	X2SON (DPW) | 5	3000 | LARGE T&R	-	Call TI	Call TI	-	
PSN74UVP1G37DRYR	Active	Preproduction	SON (DRY) | 6	3000 | LARGE T&R	-	Call TI	Call TI	-	
PSN74UVP1G37DSFR	Active	Preproduction	SON (DSF) | 6	3000 | LARGE T&R	-	Call TI	Call TI	-	

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF SN74UVP1G37 :

- Automotive : SN74UVP1G37-Q1

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

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